

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1261cs#pbf

(Engineering Calculation)

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**TOTAL MASS (g) : 0.137533**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002442	1000000	17755.6816406		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.047911	975000	348358.90625		
		Iron (Fe)	7439-89-6	0.001179	24000	8572.4609375		
		Phosphorus (P)	7723-14-0	0.000015	300	109.064376831		
		Zinc (Zn)	7440-66-6	0.000034	700	247.212615967		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.049139</b>	<b>1000000</b>	<b>357287.65625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002585	1000000	18798.609375		
		<b>External Plating Total:</b>				<b>0.002585</b>	<b>1000000</b>	<b>18798.609375</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000393	1000000	2857.48681641		
<b>Internal Plating Total:</b>				<b>0.000393</b>	<b>1000000</b>	<b>2857.48681641</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000784	750000	5700.43164062		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000261	250000	1897.72033691		
<b>Die Attach Total:</b>				<b>0.001045</b>	<b>1000000</b>	<b>7598.15234375</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.012258	150000	89127.4140625		
		Bromine (Br)	40039-93-8	0.000817	10000	5940.37353516		
		Silica (SiO2)	60676-86-0	0.066193	810000	481286.59375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.002452	30000	17828.3925781		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.081720</b>	<b>1000000</b>	<b>594182.8125</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000209	1000000	1519.63037109		
					<b>TOTAL MASS (g) :</b>	<b>0.137533</b>		